



# Cooperative Microsystems

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**“Cooperative Microsystems”**

**Adel A. M. Saleh**

**DARPA / MTO**

**4 March 2009**

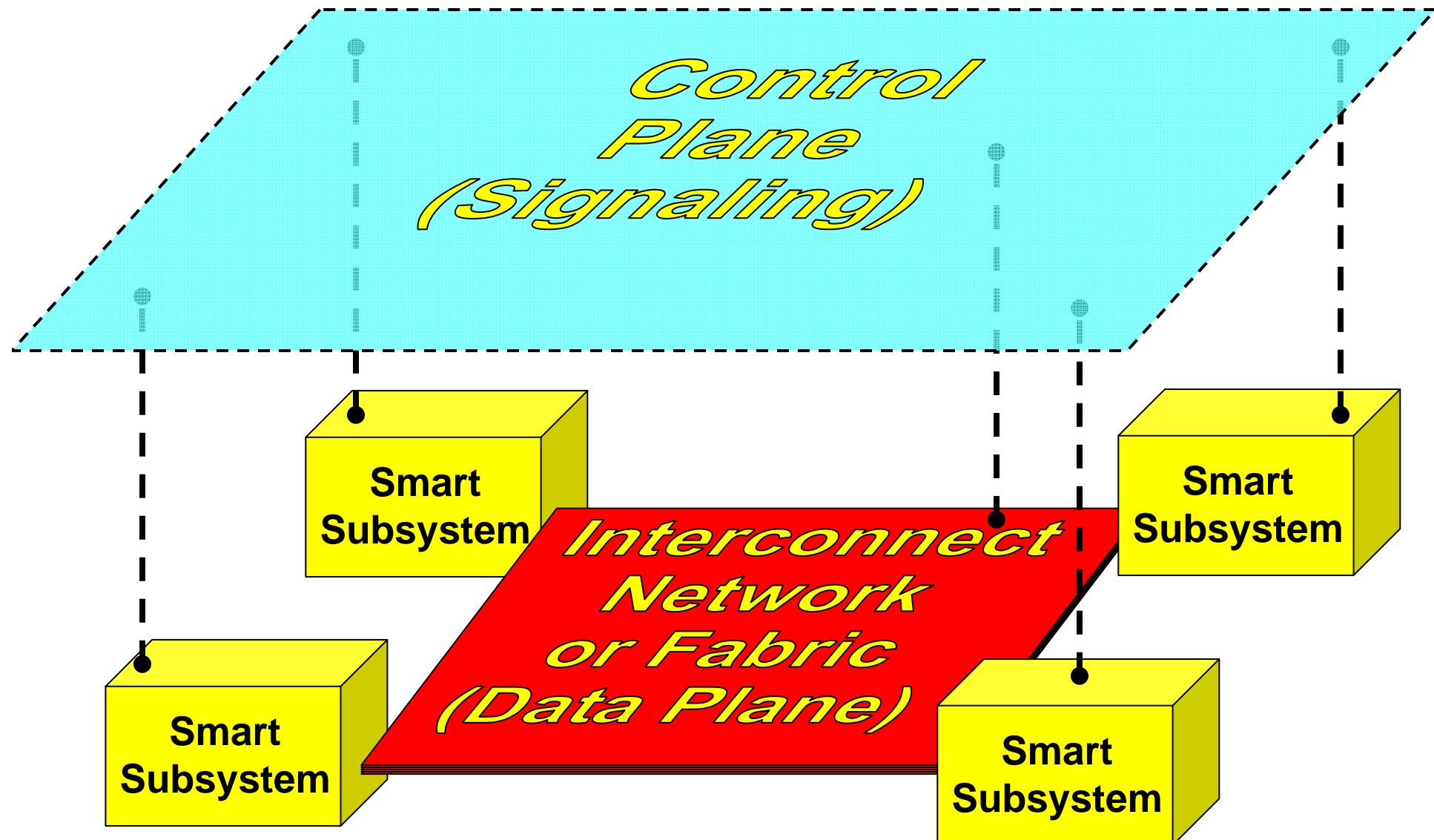


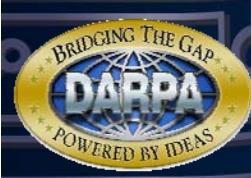
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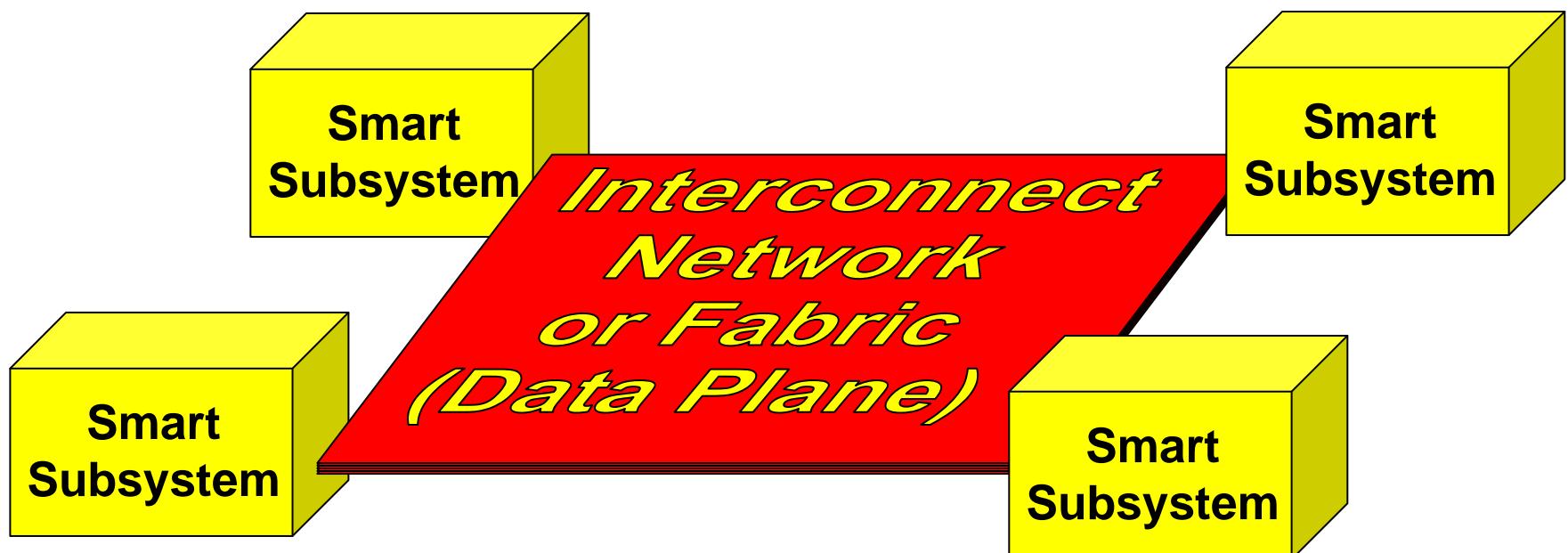


# Definition of a Cooperative System





# Definition of a Cooperative System





# A Cooperative **Mega-System** (Global-Scale IP/Optical Network)



## DARPA CORONET Program

The Network Nodes Cooperate to Accomplish:

- Fast, automatic end-to-end provisioning of IP and Optical Services
- Fast, automatic recovery from multiple network failures (self healing)
- Secure, low blocking, low latency, high efficiency, and huge capacity



# Let Us Shrink the Network by Factors of 10



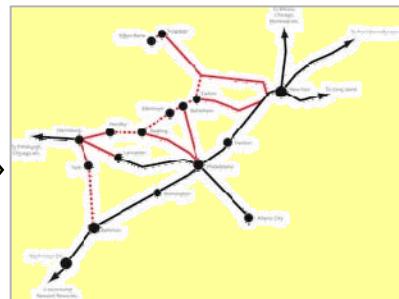
## Each Case is a Cooperative System of Its Own

~5,000 km



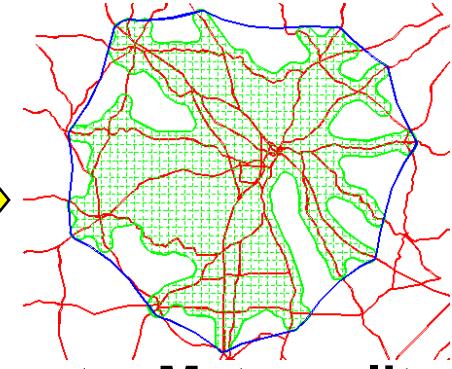
Wide-Area Network (WAN)

~500 km



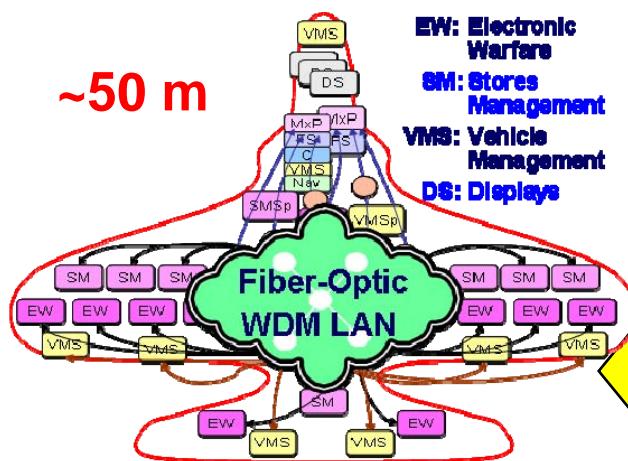
Regional Network

~50 km



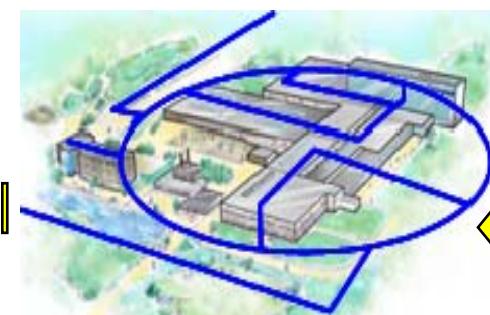
Greater Metropolitan-Area Network (MAN)

~50 m



WDM Local-Area Network (LAN) for Avionic Platforms  
DARPA NEW-HIP Program

~500 m

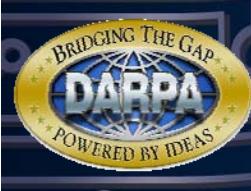


Campus-Scale Local-Area Network (LAN)

~5 km



Metropolitan-Area Network (MAN)



# Outline of the Rest of the Talk



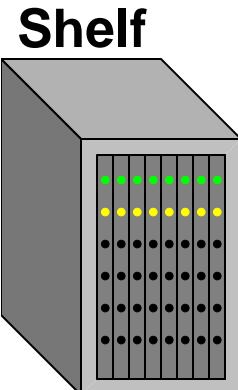
- A Vision for the Next-Generation, High-Performance Cooperative Microsystems Consisting of Chips, Cards, Shelves and Racks
- Chip-to-Chip Optical Interconnects
  - *Current and Future Vision*
- On-Chip Cooperative Microsystems
  - *We will hear two talks on this*
- Summary of the Vision
- Quantum-Scale Cooperative Microsystems
  - *We will hear two talks on this*
- Biological Cooperative Microsystems
  - *We will hear one talk on this*



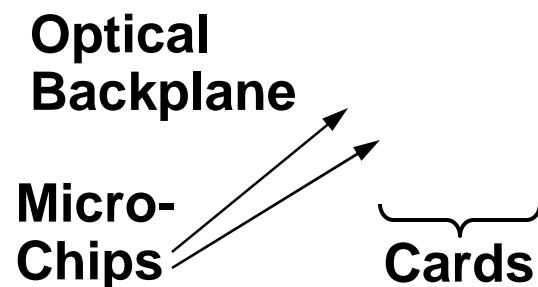
# A Vision for the Next-Generation, High-Performance Cooperative Microsystems



The Heart of the Vision is Configurable, Optical, WDM-Based Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus



Shelf



Optical  
Backplane

Micro-  
Chips

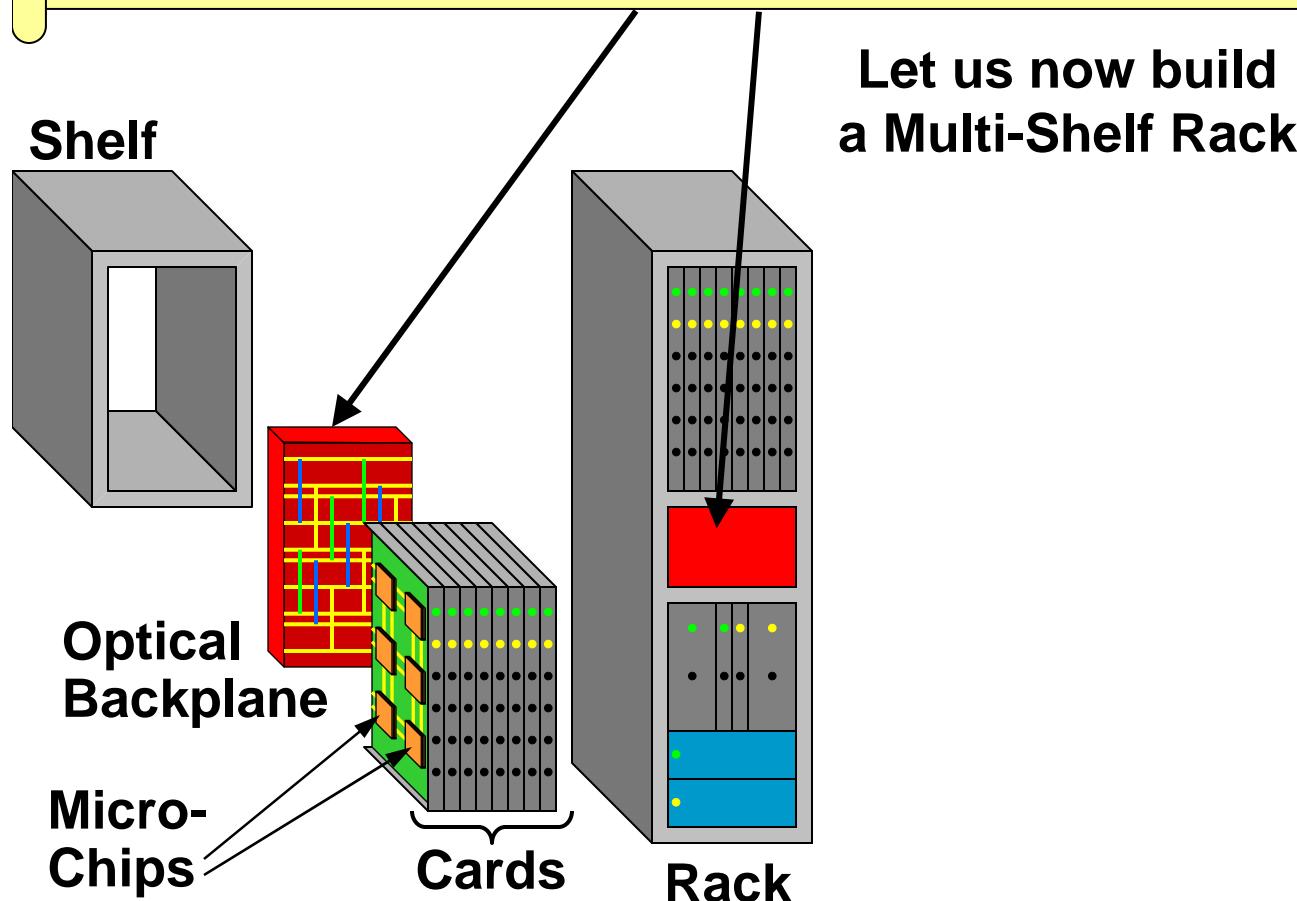
Cards



# A Vision for the Next-Generation, High-Performance Cooperative Microsystems



The Heart of the Vision is Configurable, Optical, WDM-Based Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus

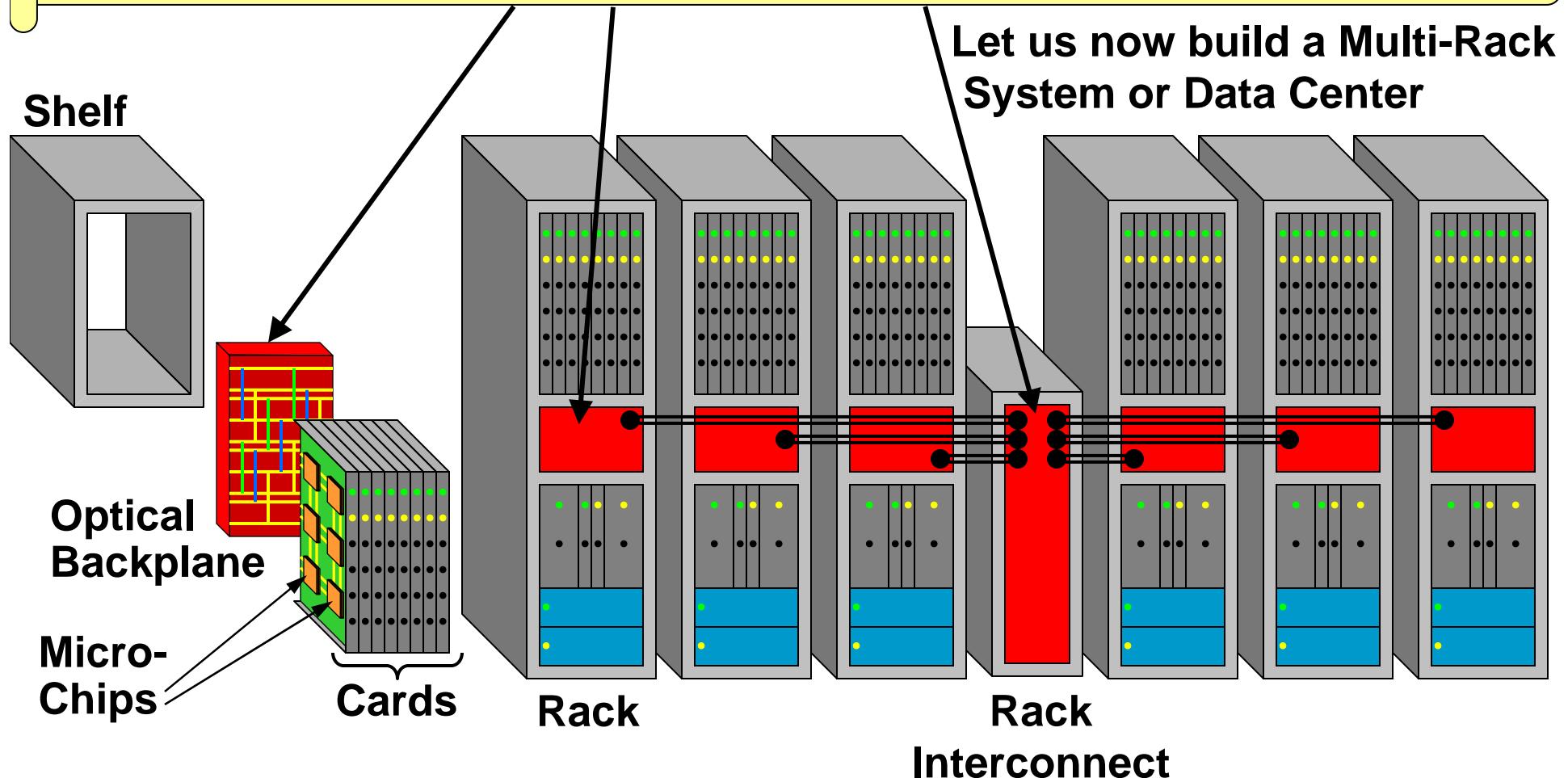




# A Vision for the Next-Generation, High-Performance Cooperative Microsystems

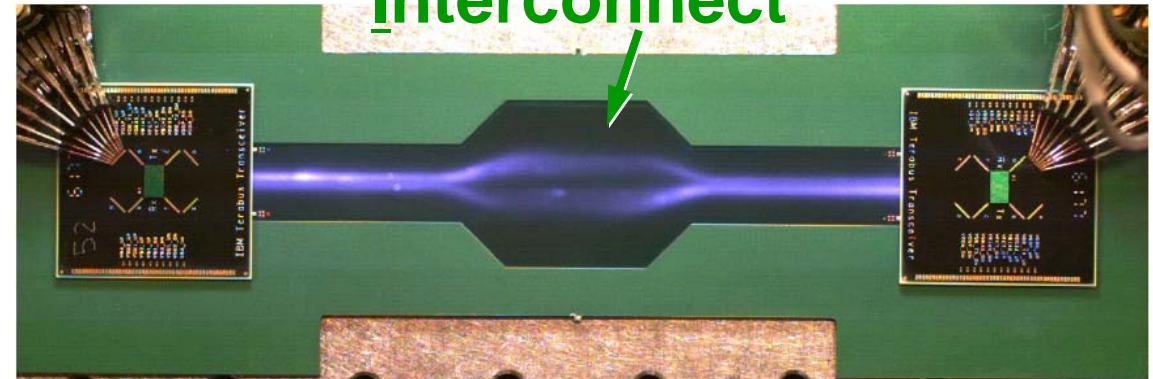
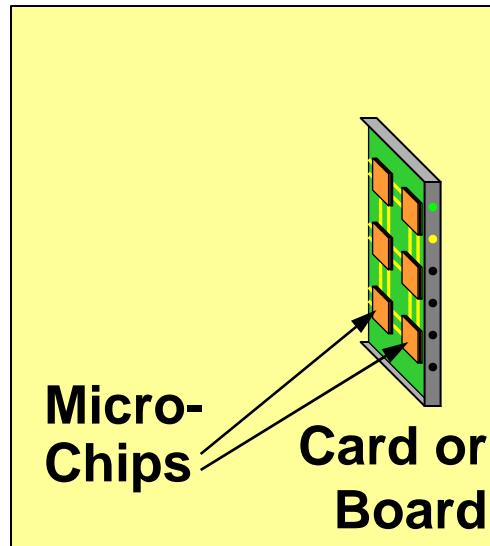


The Heart of the Vision is Configurable, Optical, WDM-Based  
Interconnects to Realize a Plug-and-Play, Multi-Terabit Bus





# Pushing the Vision Down to the Board and Chip Levels



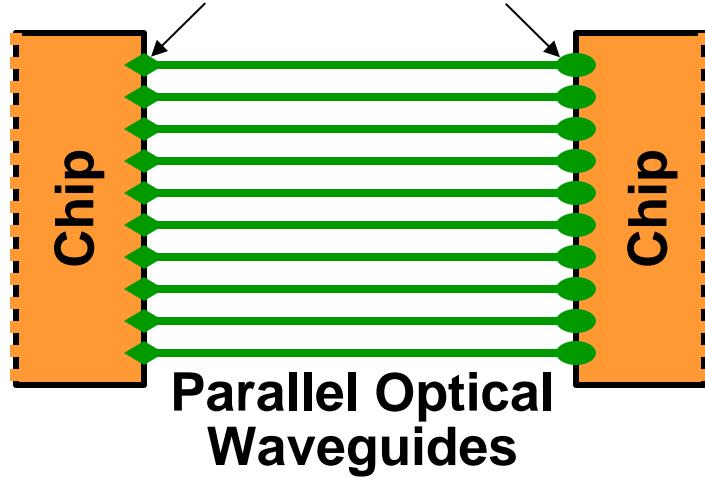
Chip-to-Chip Optical Interconnect

**The DARPA C2OI Program**

- Board-level and off-board, chip-to-chip optical communication
- Utilizing an array of VCSEL transmitters, parallel waveguides, and photo-diode receivers
- Enables higher bandwidth (>>1 Tbps) and lower power (5 pJ/bit) communication as compared to electronic alternatives.
- Do we need to add **WDM** and **Configurability** to this Vision ?

Arbitrary- $\lambda$   
Fixed  
Lasers

Photo Diodes  
with no Filters



Static, Parallel Optical Interconnect

\* Reference architecture

Multi- $\lambda$   
Sources

$\lambda_1, \lambda_2, \dots, \lambda_N$

Chip

Parallel Optical  
Waveguides

Multi- $\lambda$   
Receivers

$\lambda_1, \lambda_2, \dots, \lambda_N$

Chip

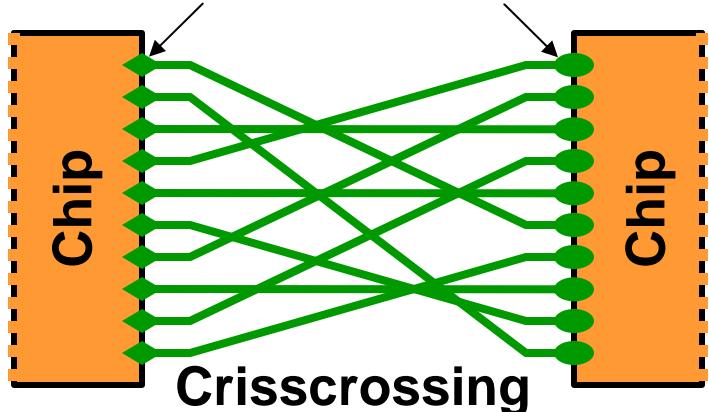
Parallel Optical  
Waveguides

Use WDM to Increase Capacity ?

- \* Multi- $\lambda$  transmitters and receiver are large and power hungry
- \* **I do not believe that this is why one would want to do WDM**

Arbitrary- $\lambda$   
Fixed  
Lasers

Photo Diodes  
with no Filters



Specific- $\lambda$ s  
Fixed Lasers

$\lambda_1, \lambda_2, \dots, \lambda_N$

Specific- $\lambda$ s  
Fixed-Filter  
Photo Diodes

$\lambda_1, \lambda_2, \dots, \lambda_N$

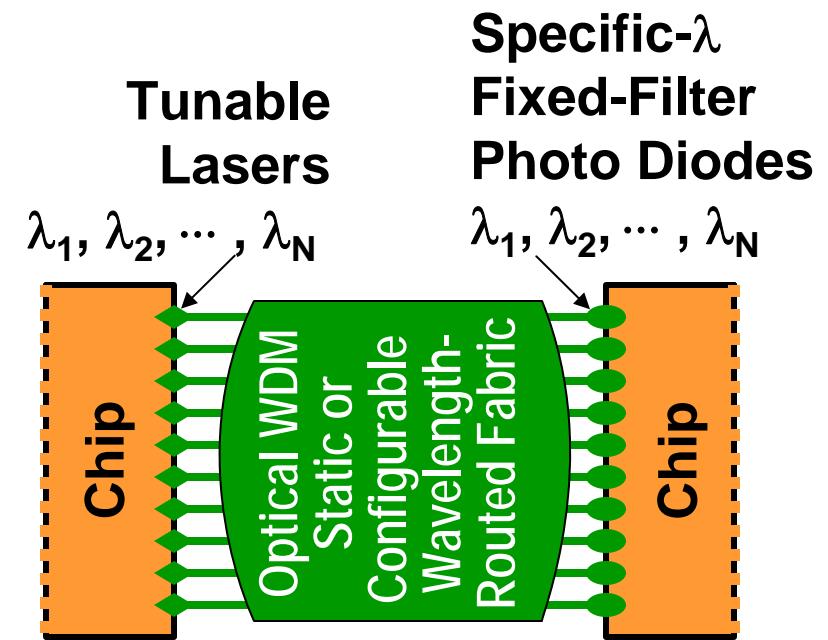
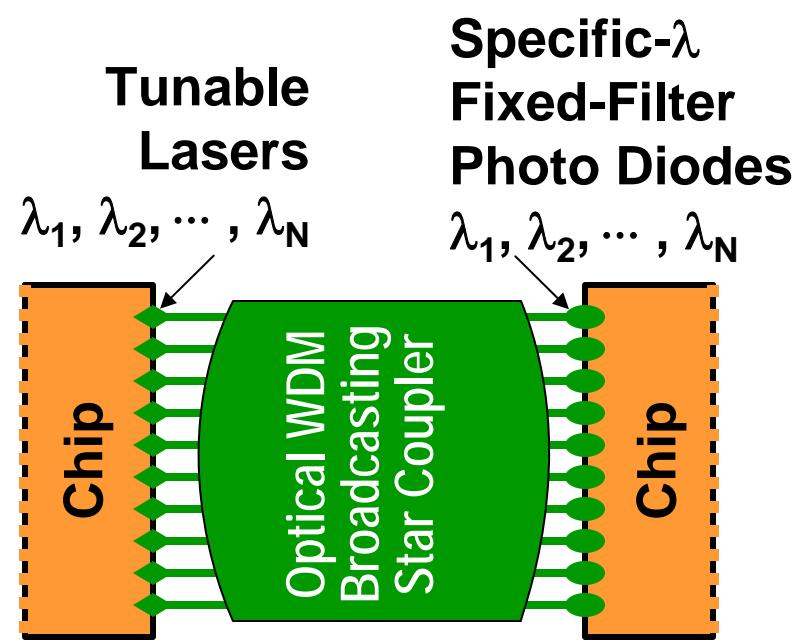


## Crisscrossing Optical Interconnect

- \* Hard to fabricate crossing waveguides with low loss and low cross-talk
- \* Once made, interconnection is static
- \* Not an elegant solution!

## Crisscrossing Optical Interconnect

- \* More elegant solution
- \* But, we need specific- $\lambda$ s, fixed lasers and filters for this vision
- \* Nominal loss =  $1/N$
- \* WDM in the fabric, not at the ends

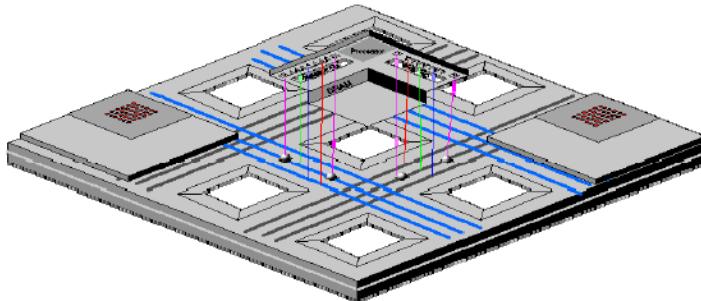


- \* We need *tunable lasers and specific- $\lambda$ s fixed filters for this vision*
- \* Nominal loss =  $1/N$
- \* *WDM in the fabric not at the ends*

- \* *Same end device requirements*
- \* *The fabric can be a static AWG or a tunable cross-bar switch*
- \* *No nominal  $1/N$  loss*
- \* *WDM in the fabric not at the ends*



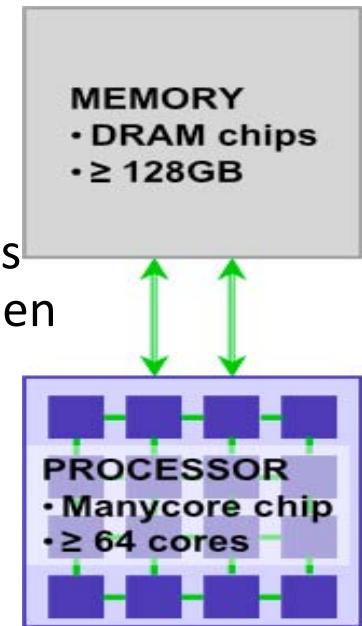
# Moving the Vision On-Chip !



**SUN Microsystems:** Macrochip design providing 10 TB/s bisection bandwidth for 64 cores providing 10 TFLOPS

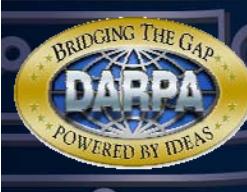
## The DARPA UNIC Program: Ultraperformance Nanophotonic Intrachip Communications

**MIT Lincoln Lab:**  
Optimization of optical communication networks among cores, and between cores and memory

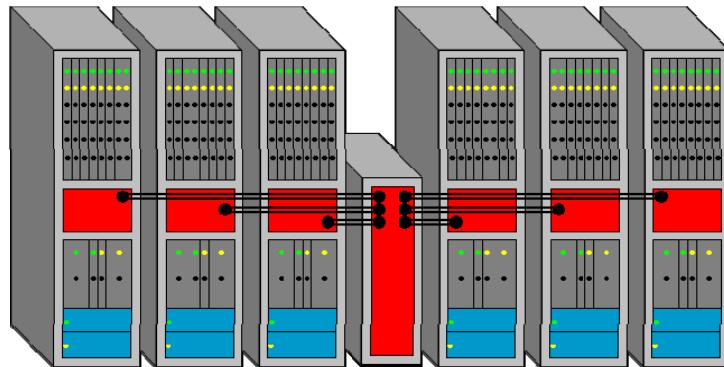


### Two Talks:

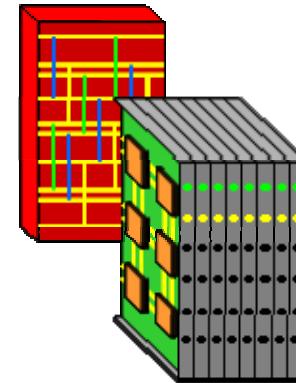
- Ashok Krishnamoorthy (SUN) – **Intrachip Photonic Communications Networks with Seamless Off-chip Communications: Vision for the Future**
- Jeremy Kepner (MIT/LL) – **Photonomically-enabled Optimized Embedded Microprocessors, Shared Memory Optimizing Multicore Cooperation**



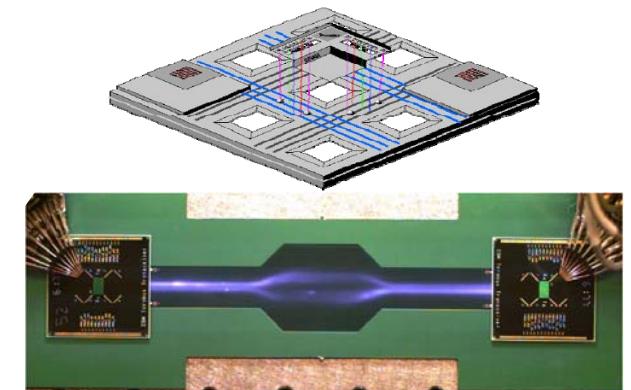
# Cooperative Systems of Various Orders of Magnitudes Benefiting from WDM Optical Networking



Intra- / Inter-Rack



Inter-Cards or Boards



Intra- / Inter-Chip

- Of course, the very same devices and components do not work at all scales of the vision
- But the same basic ideas and architectures promise higher performance (capacity and flexibility) at a reduced cost, size and power for all scales of the vision
- Much more work is needed at all scales to realize this vision of multi-terabit-per-second cooperative microsystems

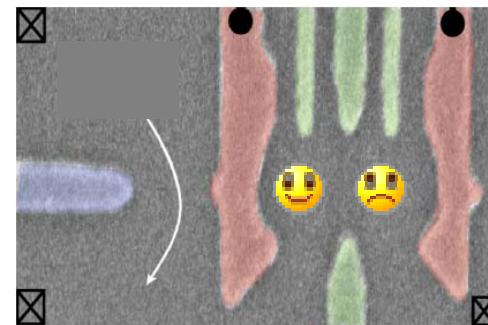


# Cooperative Microsystems at a Quantum Scale



Here, the subsystems are quantum states, e.g., electron spin states, photon polarization states, atomic states, etc., and the interconnect is quantum entanglement, “the spooky action at a distance”

Entanglement of electron spins in quantum dots defined by gate voltages

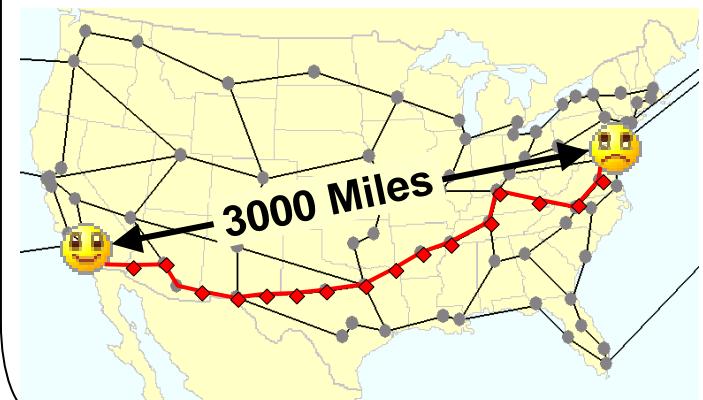


## Two Talks:

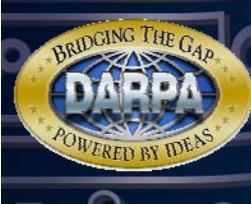
- Charles Marcus (Harvard) – **Cooperative Quantum Microsystems**
- Charles Bennett (IBM) – **The Promise of Quantum Key Distribution**

Today, scientists have succeeded in realizing secure Quantum Key Distribution (QKD) over ~100-km free-space or fiber-optic links using the **BB84 Protocol** conceived by **Bennett and Brassard** in 1984

The holy grail of QKD is to extend the distance to continental scale, using entanglement-based **“quantum repeaters”**



Part of the vision in this sub-session is related to the DARPA QuEST Program



# And finally for something completely different !



## A Talk by:

- Joe Pancrazio (NIH) – on  
**“Prosthetics, Interconnects,  
Neuro-Photonics”**

Note that *Interconnects* is a common theme,  
other than that, it is a completely different story

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FROM THE INSIDE OUT

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